

Product Change Notice (PCN)

Subject: Transfer of the Solder Plating Site from Carsem S-Site to Carsem M-Site for the Listed Renesas Products

Publication Date: 8/8/2019

Effective Date: 11/8/2019

Revision Description:

Initial Release

Description of Change:

Carsem is discontinuing the SnPb plating process at their S-Site and transferring the product to their M-Site location in Ipoh Malaysia.

Products Impacted:

<u>Renesas Part Number</u>	<u>Vendor Item Drawing Number</u>
ISL3282EMRTEP-TK	V62/10601-01XB
ISL3298EMRTEP-TK	V62/10602-01XB

Reason for Change:

Carsem S-site discontinuing SnPb Plating process due to underutilization. Products plated at Carsem S-Site are being moved to Carsem M-Site to better utilize existing capacity and capability.

Impact on fit, form, function, quality & reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

Product affected by this change is identifiable via the Renesas internal traceability system.

Qualification status: Complete, see attached

Sample availability: 8/8/2019

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@INTERSIL.COM	Europe: PCN-EU@INTERSIL.COM	Japan: PCN-JP@INTERSIL.COM	Asia Pac: PCN-APAC@INTERSIL.COM

Appendix A - Qualification Results (see attached)

Appendix A:

3 Qualification lots from Carsem (M-Site) at 3 different dates for Solder Plating.

Lot details as below:

LD	PKG	DEVICE	CSM M PLATE DATE	LOT_QTY
8	MLPD2X3W	ISL3282EMRTEP-TK	2019 Apr 15	1999
8	MLPD2X3W	ISL3282EMRTEP-TK	2019 Apr 23	1985
8	MLPD2X3W	ISL3282EMRTEP-TK	2019 Apr 18	2000

Plating thickness / composition:

Plating thickness spec: 300- 1000 micro inch

Plating composition spec: 70 – 90 % Sn (balance Pb)

Measuring equipment: XRF machine

Plating Parameter used: 120 +/- 10 Amp (similar to S site setting, same machine model at M site)

S/size: 6 unit/lot

SUBLOT SERIAL NUMBER	PLATING THICKNESS READING (MICRO INCH)						MIN	MAX	MEAN
	1	2	3	4	5	6			
S201851105512-01	497	535	521	556	501	499	497	556	518
S201851105513-01	511	565	489	543	529	533	489	565	528
S201851105514-01	516	542	555	562	526	543	516	562	540

SUBLOT SERIAL NUMBER	PLATING COMPOSITION (% Sn)						MIN	MAX	MEAN
	1	2	3	4	5	6			
S201851105512-01	84	84	85	84	86	84	84	86	85
S201851105513-01	85	85	84	84	85	84	84	85	84
S201851105514-01	84	85	86	86	85	85	84	86	85

Plating visual inspections:

Plating inspection method: Scope 30X magnification

S/size: 100 % inspections for each lot upon received at S site (after complete plating at M site)

SUBLOT SERIAL NUMBER	QTY UNITS	QTY FRAME	PLATING DEFECT: UNITS	DEFECT PPM
S201851105512-01	1985	2 FRAME	0	0
S201851105513-01	2000	2 FRAME	0	0
S201851105514-01	1999	2 FRAME	0	0

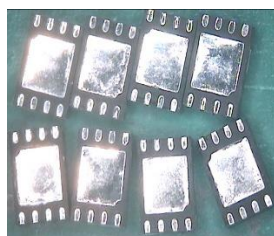
Solderability Test:

Solder pot type: Sn /Pb

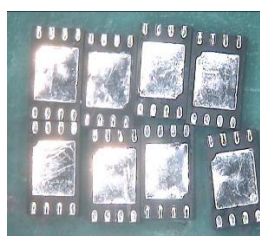
Solder pot temp: 245 +/- 5 DegC

Precondition: Normal test (no precondition)

S/size: 22 unit /lot.



S201851105512-01



S201851105513-01



S201851105514-01

All the 22 units/lot passed normal solderability test with good wetting.

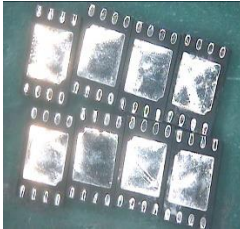
Solderability Test (16-hour dry bake @ 150DegC):

Solder pot type: Sn /Pb

Solder pot temp: 245 +/- 5 DegC

Precondition: 16-hour Dry Bake @ 150 Deg C

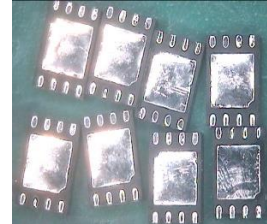
S/size: 22 unit /lot.



S201851105512-01



S201851105513-01



S201851105514-01

All the 22 units/lot passed 16hrs dry bake solderability test with good wetting.

Solderability Test (16-hour Steam Age):

Solder pot type: Sn /Pb

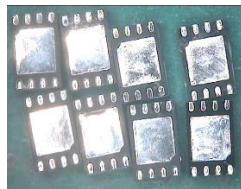
Solder pot temp: 245 +/- 5 DegC

Precondition: 16-hour Steam Age

S/size: 22 unit /lot.



S201851105512-01



S201851105513-01



S201851105514-01

All the 22 units/lot passed 16hr steamage solderability test with good wetting.